

KL IR 15 – run sheet

KemLab, Inc.

nanyte.com/photoresists/kl-ir · last updated 2026-07-26

Thickness: 1.2–2.6 μm

Softbake: 105 °C · 1.5 min · hotplate

Post-exposure bake: 115 °C · 60 s

Develop: Developer 0.26N TMAH · Time 45–60 s · Method puddle